

IN THE CLAIMS:

The following is a listing of all the claims as they currently stand. Kindly amend claims 1-10 and 15-21, cancel claim 11 and add claims 23-28, as noted below.

1. (Currently amended) An assembly comprising an EMI/RFI shield integrally formed in a thermoformable sheet, wherein portions of the thermoformable sheet are removed around a periphery of the EMI/RFI shield, ~~wherein such that~~ the portions of the thermoformable sheet that are not removed integrally connect the EMI/RFI shield to a remainder of the thermoformable sheet.
2. (Currently amended) The assembly EMI/RFI shield of claim 1 wherein the EMI/RFI shield comprises at least one layer of a conductive material.
3. (Currently amended) The assembly EMI/RFI shield of claim 2 wherein the EMI/RFI shield is multi-compartmentalized.
4. (Currently amended) The assembly EMI/RFI shield of claim 2 wherein the EMI/RFI shield defines a single compartment.
5. (Currently amended) The assembly EMI/RFI shield of claim 2 wherein the layer of conductive material comprises at least one layer of tin, aluminum, copper, and nickel.
6. (Currently amended) The assembly EMI/RFI shield of claim 5 wherein the conductive material comprises a vacuum metallized first layer of tin and an electroplated second layer of tin.

7. (Currently amended) The assembly EMI/RFI shield of claim 1 wherein the thermoformable polymer sheet comprises a recycled, conductively coated polymer EMI/RFI shield that has been mechanically disintegrated and then recombined back into the formable polymer sheet.

8. (Currently amended) The assembly EMI/RFI shield of claim 7 where the mechanically disintegrated EMI/RFI shields comprise a metallized film comprising one of a painted film, a vacuum metallized film, and an electroless plated film.

9. (Currently amended) The assembly EMI/RFI shield of 1 wherein the EMI/RFI shield comprises a top surface, a plurality of sidewalls extending at an angle from the top surface and a flange around a periphery of the side walls, wherein the flange and the top surface define substantially parallel planes.

10. (Currently amended) A reel of material for in-line processing equipment, the reel comprising:

a sheet of substantially planar material;
a spool that receives the sheet of substantially planar material; and
a plurality of non-planar EMI/RFI shields integrally formed with the sheet of substantially planar material and removably attached to the sheet of substantially planar material that is rolled on the spool.

11. (Canceled)

12. (Original) The reel of material of claim 11 wherein the EMI/RFI shields are attached to the sheet of material with tabs of material.

13. (Original) The reel of material of claim 10 wherein the EMI/RFI shields comprise at least one layer of conductive material.

14. (Original) The reel of material of claim 10 wherein the EMI/RFI shields and sheet of material comprise recycled material.

15. (Currently amended) A method for forming an ~~An~~ EMI/RFI shield integrally attached to a formable polymer sheet, ~~the formed by a~~ method comprising:
shaping the formable polymer sheet to create at least one EMI/RFI shield;
applying a conductive layer to the formable polymer sheet; and
removing a portion of the material around a periphery of the conductive EMI/RFI shield so as to leave the EMI/RFI shield integrally attached to a remainder of the formable polymer sheet.

16. (Currently amended) The method EMI/RFI shield of claim 15 wherein the shaping is carried out before the applying the conductive layer.

17. (Currently amended) The method EMI/RFI shield of claim 15 wherein the shaping is carried out after applying the conductive layer.

18. (Currently amended) The method EMI/RFI shield of claim 15 further comprising applying a gasket to the EMI/RFI shield.

19. (Currently amended) The method EMI/RFI shield of claim 15 comprising forming the polymer sheet from recycled material that comprises conductive material.

20. (Currently amended) The method EMI/RFI shield of claim 15 wherein removing a portion comprises leaving tabs of material that integrally connect the EMI/RFI shield to the formable polymer sheet.

21. (Original) The EMI/RFI shield of claim 5 wherein the conductive material comprises a vacuum metallized first layer of tin and an electroplated second layer of nickel.

22. (Original) The reel of material of claim 12 wherein the tabs of material are perforated.

23. (New) The assembly of claim 1 wherein the thermoformable sheet comprises a conductive polymer.

24. (New) A sheet comprising;
a polymer sheet comprising an opening;
an EMI/RFI shield disposed within the opening such that there is a spacing between a periphery of the EMI/RFI shield and the polymer sheet;
a plurality of tabs spaced around at least a portion of the periphery of the EMI/RFI shield to connect the EMI/RFI shield to the polymer sheet.

25. (New) The sheet of claim 24 wherein the EMI/RFI shield extends above a plane defined by a top surface of the polymer sheet.

26. (New) The sheet of claim 24 wherein the EMI/RFI shield comprises side walls that extend at an angle from the plane defined by the top surface of the polymer sheet.

27. (New) The sheet of claim 26 wherein the EMI/RFI shield comprises a flange that is coupled to the side walls, the flange extending in a plane that is substantially parallel to the plane defined by the top surface of the polymer sheet.

28. (New) The sheet of claim 24 wherein the EMI/RFI shield comprises a conductive layer disposed on at least one surface.

29. (New) The sheet of claim 24 wherein the polymer sheet is conductive.